

Title (en)
Resin encapsulated device

Title (de)
Vergussgekapselte Vorrichtung

Title (fr)
Dispositif encapsulé en résine

Publication
EP 0989567 B1 20020626 (DE)

Application
EP 99116313 A 19990819

Priority
DE 19843673 A 19980923

Abstract (en)
[origin: EP0989567A1] The arrangement has a coil (70) embedded in a setting material (12) in a housing (10) and an iron circuit (60) connected to external leads via contact elements (20) likewise embedded in setting material and mounted inside the housing. The contact elements protrude beyond the setting material closing the end of the housing into a hollow chamber formed by a curved cover element attached to the housing near the contact elements. A cable channel in the setting material communicates with the hollow chamber.

IPC 1-7
H01F 7/06

IPC 8 full level
H01F 7/06 (2006.01)

CPC (source: EP US)
H01F 7/06 (2013.01 - EP US)

Citation (examination)
CH 627584 A5 19820115 - LUCIFER SA [CH]

Cited by
EP1569248A3; DE10125223A1; DE10125223B4

Designated contracting state (EPC)
CH DE FR GB IT LI

DOCDB simple family (publication)
EP 0989567 A1 20000329; EP 0989567 B1 20020626; DE 19843673 A1 20000413; DE 19843673 C2 20010517; DE 59901840 D1 20020801; US 6246309 B1 20010612

DOCDB simple family (application)
EP 99116313 A 19990819; DE 19843673 A 19980923; DE 59901840 T 19990819; US 40406899 A 19990923